

REMARKS/ARGUMENTS

Claims 1-5, 9-10, 13-16, and 18-26 are active. Claims 10, 16, and 18-23 stand withdrawn.

Claim 1 is amended to incorporate Claim 8.

Claim 2 is amended for clarity.

Claims 10 and 16 have been amended consistent with Claim 1 so that the Office may consider rejoinder upon finding the elected claims allowable.

Claim 13 is amended to incorporate the salient features from Claim 10.

Claim 15 is amended to remove the "such as" phrasing and now presented in new claims 24-26. Withdrawal of the 112, second paragraph rejection is requested.

A substitute Abstract is provided as required in the Action.

No new matter is added.

The rejection of Claims 1-5 under 35 USC 102(b) citing Levon and the rejections applied under 35 USC 102(b) citing Geng or Cao are not sustainable. Specifically, none of these three citations describe the combination of the substituted or unsubstituted polyaniline complex pronated by a sulfosuccinate of formula III, a compound having a phenolic hydroxyl group and an organic solvent substantially immiscible with water.

Indeed, this fact has already been acknowledged for the rejection applying Levon, as Claim 8 (which has been incorporated into Claim 1) was not rejected.

Cao describes conductive films formed with a solution of polyaniline with various phenolic compounds as a solvating ligand dissolved in a nonpolar or weakly polar solvent, and the highest conductivity of these conductive films is 25.6 S/cm (see Table 5). Cao discloses polyaniline, DBSA (dopant) and additional DBSA (solvating ligand) as well as polyaniline, DBSA (dopant) and phenolic compound (solvating ligand) dissolved in a

nonpolar solvent such as toluene. Geng discloses polyaniline and CSA (dopant) dissolved in cresol or chloroform.

Neither Geng nor Cao describe, nor has the Office pointed to any disclosure that establishes that Geng and Cao describe, the combination of the substituted or unsubstituted polyaniline complex pronated by a sulfosuccinate of formula III, a compound having a phenolic hydroxyl group and an organic solvent substantially immiscible with water.

Accordingly, the anticipation rejections applied under 35 USC 102(b) cannot be sustained.

To the alternative rejections applied under 35 USC 103(a) citing Geng or Cao, the rejections cannot be sustained. As already explained above, the rejection does not point to disclosure nor explain why the salient limitations of Claim 8 (incorporated into Claim 1) are taught or suggested by Geng or Cao. The Office has the initial burden of proof to establish the *prima facie* obviousness of the subject matter Applicants claim in view of the prior art teaching. *In re Fritch*, 972 F.2d 1260, 1265 (Fed. Cir. 1992); *In re Fine*, 837 F.2d 1071, 1074 (Fed. Cir. 1988). Absent evidence which supports a rejection of the subject matter Applicants claim for obviousness, the Examiner's conclusion that Applicants' claims are unpatentable under 35 U.S.C. §103(a) must be withdrawn.

Notwithstanding the deficiencies of the rejections, Applicants explain why the claims are not obvious in view of either Geng or Cao.

As explained on pages 4-5 of the present application, the inventors have found that the claimed complex is soluble in the defined organic solvent and that the organic solvent phase can be homogeneously applied to a substrate such as glass. In addition, surprisingly, it was found that polyaniline with a very large molecular weight can be produced, in spite of its properties of being dissoluble in solvents such as toluene. Furthermore, the inventors found

that a molded article of the conductive polyaniline composition exhibits outstandingly improved electrical characteristics such as electric conductivity.

Cao further discloses that when a nonpolar or weakly polar solvent is the solvent, an acidic substance (a sulfonic acid, a phenolic compound, etc.) acts as a solvating ligand to increase solubility of the polyaniline (see p.187, Introduction, lines 39—45)

Cao describes a conductive film prepared using a solution of the polyaniline protonated by using DBSA as a solvating ligand dissolved in a nonpolar or weakly polar solvent and a conductive film prepared with a solution of that polyaniline.

Cao teaches that the conductivity of the film formed from the solution using DBSA as a solvating ligand increases up to 88.0 S/cm while conductivity of the film formed from the solution to which no additional DBSA is added is 11.7 S/cm (see Table 4). Cao also describes conductive films with various phenolic compounds as a solvating ligand dissolved in a nonpolar or weakly polar solvent, and the highest conductivity of these conductive films is 25.6 S/cm (see Table 5).

Cao thus describes that the acidity of the solvating ligand is important (see Table 4) and that solvating ligand preferable to increase conductivity has a higher acidity (see from p.189, right column, line 3 from the bottom to p.190, left column, line 11).

Geng discloses polyaniline and CSA (dopant) dissolved in cresol or chloroform.

Thus, not only is there no disclosure for the claimed combination of features (see amended Claim 1), the invention defined in the claims include a phenolic compound with a low acidity (see Claim 1 phenolic hydroxyl group and Claim 14) and achieved a high conductivity (see Example of the present application, conductivity as high as 300 S/cm). Indeed, Cao's teachings that a higher acidity compound is important teach one away from the present invention.

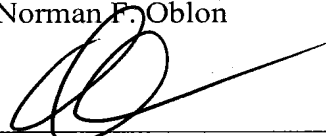
The conductivity value of 300 S/cm (see Example 2, page 39 of the present application) where cresol is the solvating ligand, is significantly higher than the highest value of 25.6 S/cm in Cao when the phenolic compound is the solvating ligand. Such an increase would not have been reasonably predictable.

In view of the above discussion, Applicants request that the rejections applied under 35 USC 103(a) be withdrawn.

A Notice of Allowance for all pending claims, after rejoining the non-elected claims, is requested.

Respectfully submitted,

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